

High Voltage Standard Rectifier

2200 V V_{RRM}

30 A

 V_{F} 1.24 V

Single Diode

Part number

DNA30ER2200IY



Backside: anode



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very low forward voltage drop
- Improved thermal behaviour

Applications:

- Diode for main rectification
- For single and three phase bridge configurations

Package: TO-262 (I2Pak)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Terms _Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact the sales office, which is responsible for you.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the product in aviation, in health or live endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

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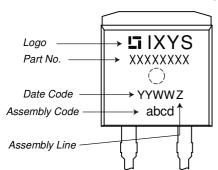
Rectifier				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM}	max. non-repetitive reverse bloc	cking voltage	$T_{VJ} = 25^{\circ}C$			2300	V
V _{RRM}	max. repetitive reverse blocking	voltage	$T_{VJ} = 25^{\circ}C$			2200	V
I _R	reverse current	V _R = 2200 V	$T_{VJ} = 25^{\circ}C$			40	μΑ
		$V_R = 2200 \text{ V}$	$T_{VJ} = 150$ °C			1.5	mΑ
V _F	forward voltage drop	I _F = 30 A	$T_{VJ} = 25^{\circ}C$			1.26	٧
		$I_F = 60 \text{ A}$				1.53	٧
		I _F = 30 A	T _{VJ} = 150 °C			1.24	V
		$I_F = 60 \text{ A}$				1.63	٧
I FAV	average forward current	T _C = 140°C	$T_{VJ} = 175$ °C			30	Α
		rectangular d = 0.5					i ! !
V _{F0}	threshold voltage		T _{vJ} = 175°C			0.83	V
r _F	slope resistance \(\) for power	loss calculation only				13.4	mΩ
R _{thJC}	thermal resistance junction to ca	ase				0.7	K/W
R _{thCH}	thermal resistance case to heats	sink			0.50		K/W
P _{tot}	total power dissipation		$T_{C} = 25^{\circ}C$			210	W
I _{FSM}	max. forward surge current	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			370	Α
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			400	Α
		t = 10 ms; (50 Hz), sine	T _{VJ} = 150°C			315	Α
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			340	Α
l²t	value for fusing	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			685	A2s
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			665	A²s
		t = 10 ms; (50 Hz), sine	$T_{VJ} = 150$ °C			495	A ² s
		t = 8.3 ms; (60 Hz), sine	$V_R = 0 V$			480	A²s
CJ	junction capacitance	$V_{R} = 700 \text{ V}; f = 1 \text{ MHz}$	$T_{VJ} = 25^{\circ}C$		7		pF





Package TO-262 (I2Pak)				Ratings			
Symbol	Definition Conditi	ons	min.	typ.	max.	Unit	
I _{RMS}	RMS current per termi	inal			35	Α	
T _{VJ}	virtual junction temperature		-55		175	°C	
T _{op}	operation temperature		-55		150	°C	
T _{stg}	storage temperature		-55		150	°C	
Weight				1.5		g	
F _c	mounting force with clip		20		60	N	
d _{Spp/App}	creepage distance on surface striking distance thro	terminal to terminal	4.2			mm	
d _{Spb/Apb}	creepage distance on surface striking distance throt	terminal to backside	4.9			mm	

Product Marking



Part description

D = Diode N = High Voltage Standard Rectifier

A = (>= 2000V)

30 = Current Rating [A]

ER = Single Diode

2200 = Reverse Voltage [V] IY = TO-262 (I2Pak) (2HV)

Order	ng	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standa	ard	DNA30ER2200IY	DNA30ER2200IY	Tube	50	513702

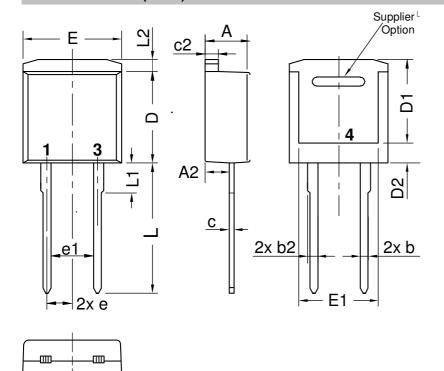
Similar Part	Package	Voltage class
DNA30E2200PA	TO-220AC (2)	2200
DNA30E2200PZ	TO-263AB (D2Pak) (2HV)	2200
DNA30EM2200PZ	TO-263AB (D2Pak) (2HV)	2200
DNA30E2200FE	i4-Pac (2HV)	2200

Equiv	alent Circuits for	Simulation	* on die level	$T_{VJ} = 175 ^{\circ}\text{C}$
$I \rightarrow V_0$	$-R_0$	Rectifier		
V _{0 max}	threshold voltage	0.83		V
R _{0 max}	slope resistance *	10.2		mΩ





Outlines TO-262 (I2Pak)



Dim.	Millimeter		Inches		
DIIII.	min	max	min	max	
Α	4.06	4.83	0.160	0.190	
A2	2.41		0.095		
b	0.51	0.99	0.020	0.039	
b2	1.14	1.40	0.045	0.055	
С	0.40	0.74	0.016	0.029	
c2	1.14	1.40	0.045	0.055	
D	8.38	9.40	0.330	0.370	
D1	8.00	8.89	0.315	0.350	
D2	2	.5	0.098		
Е	9.65	10.41	0.380	0.410	
E1	6.22	8.50	0.245	0.335	
е	2,54 BSC		0,100 BSC		
e1	4.	28	0.169		
L	13.00	13.60	0.512	0.535	
L1	2.90	3.10	0.114	0.122	
L2	1.02	1.68	0.040	0.066	

All dimensions conform with and/or within JEDEC standard.





Rectifier

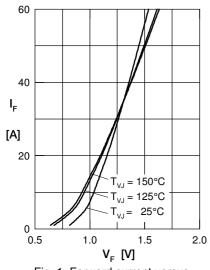


Fig. 1 Forward current versus voltage drop per diode

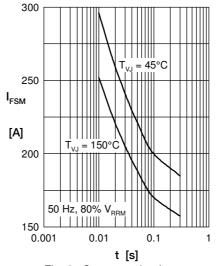


Fig. 2 Surge overload current

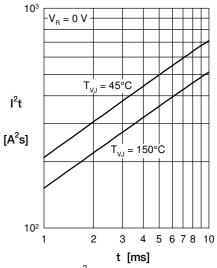


Fig. 3 I²t versus time per diode

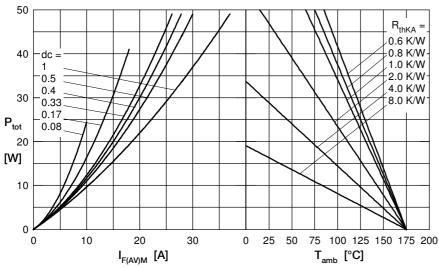


Fig. 4 Power dissipation versus direct output current and ambient temperature

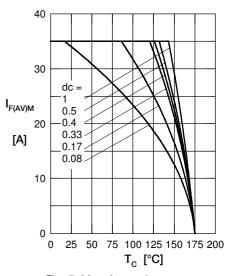


Fig. 5 Max. forward current versus case temperature

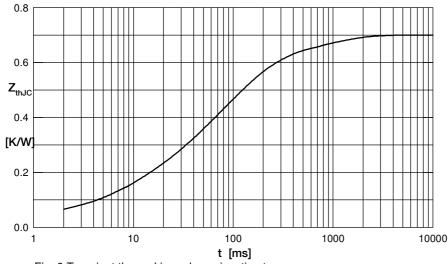


Fig. 6 Transient thermal impedance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t _i (s)
1	0.03	0.0003
2	0.072	0.0065
3	0.131	0.027
4	0.367	0.105
5	0.1	8.0